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Oggetto : SECO and Qualcomm highlight Qualcomm Dragonwing Edge AI platforms at embedded world 2026

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PRESS RELEASE

## SECO and Qualcomm highlight Qualcomm Dragonwing Edge AI platforms at embedded world 2026

### From high-performance COM Express modules to scalable industrial HMIs and Edge AI systems

Arezzo, February 26, 2026 – At embedded world 2026 (March 10–12, Nuremberg), SECO S.p.A. (“SECO” or the “Company”) will showcase Edge AI solutions powered by Qualcomm Dragonwing™ platforms, demonstrating how its hardware, software, and Clea ecosystem enable secure, high-performance, cloud-independent applications.

#### SOM-COMe-CT6-Dragonwing-IQ-X: redefining high-performance industrial edge computing

At the center of SECO's Qualcomm-based portfolio is the [SOM-COMe-CT6-Dragonwing-IQ-X](#), a high-performance COM Express Type 6 module based on the Qualcomm Dragonwing IQ-X Series, designed to **enable industrial PCs, advanced HMIs, and AI-driven automation without trade-offs between performance, power efficiency, and system complexity**. Powered by 12- or 8-core Qualcomm® Oryon™ CPUs with up to 3.4 GHz single-thread performance and up to 45 TOPS of on-device AI acceleration, it supports real-time control, analytics, and high-resolution visualization with low power consumption, enabling compact, fanless designs. Optimized for vision-intensive applications, it supports multiple cameras, dual ISPs, displays up to 2× 5K or 4× 4K, and high-speed I/O including USB4, PCIe, and UFS 4.0 for fast system integration. Designed for harsh industrial environments, the module operates from –40°C to +85°C, supports Windows 11 IoT Enterprise LTSC, and meets long-term industrial lifecycle requirements. Combined with SECO's BSPs, integration services, and the [Clea software framework](#), it provides a scalable foundation for industrial automation and advanced HMI platforms.

SECO confirms its roadmap expansion across the Qualcomm Dragonwing IQ Series with the development of SMARC solutions based on Qualcomm Dragonwing IQ8 and COM-HPC Mini platforms based on Qualcomm Dragonwing IQ9. These AI-optimized solutions are designed to support advanced Clea-enabled applications and next-generation industrial systems, bringing real-time intelligence, edge computing, and machine learning closer to industrial operations. The SMARC IQ8 and COM-HPC Mini IQ9 solutions are planned to be available by Q3 2026.

#### Modular Vision with Qualcomm Dragonwing QCS6490: real-time Edge AI for industrial automation

One of the highlights at the SECO booth will be the [Modular Vision based on Dragonwing QCS6490](#), available in 10.1-inch and 15.6-inch versions for next-generation industrial automation. Designed as a compact industrial HMI, it combines computer vision, voice command processing, and intuitive user interaction in a single device to enable smarter factory operations. Integration with Clea provides a secure foundation for device management, OTA updates, and lifecycle support.

The solution will be demonstrated through **a live experience showcasing real-time, cloud-independent AI use cases such as plant management, alert handling, and AI-based quality inspection, all running locally at the edge with ultra-low latency**. Pre-orders are now open and available [on this page](#), supporting a fast transition from evaluation to deployment.



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### Scalable SMARC platforms and real-world Edge AI use cases

To address higher-performance Edge AI requirements, SECO will present its **SMARC portfolio based on Dragonwing QCS6490 and Qualcomm Dragonwing QCS5430**, positioned as flexible and efficient building blocks for embedded and industrial AI systems.

**A key use case showcased at embedded world is MUSAI, a modular underwater AI system** powered by [SOM-SMARC-QCS6490](#). MUSAI performs real-time computer vision and object classification at the edge, demonstrating reliable AI inference on Dragonwing QCS6490-based SMARC platforms in power and connectivity-constrained environments. Integrated with **Clea**, it enables secure data management and visualization through a dedicated dashboard, showcasing a production-ready edge-to-cloud architecture for scalable monitoring and fleet management.

### Modular Link IQ-615: Intelligent Edge Systems for Smart Grid and Industrial Infrastructure

SECO will also present [Modular Link IQ-615](#), a compact DIN-rail industrial gateway for smart grid and industrial infrastructure applications, built on the **Qualcomm Dragonwing IQ-6 Series (IQ-615)**. Based on an octa-core Qualcomm® Kryo™ 460 CPU, it supports data acquisition, local processing, and secure connectivity, integrating key industrial interfaces, eMMC storage, TPM 2.0, and SECO Clea OS (Linux Yocto). Designed for harsh environments, it operates from -40°C to +80°C with power consumption below 20 W and, integrated with Clea, enables secure edge-to-cloud communication, remote device management, and OTA updates for scalable industrial and energy infrastructure solutions.

### Software enablement and end-to-end AI deployment pipeline

All Dragonwing-based solutions showcased by SECO are supported by a comprehensive software enablement stack designed to accelerate AI adoption at the edge. Through the SECO [Application Hub](#), customers can access ready-to-deploy AI and IoT applications optimized for Dragonwing platforms, while the SECO [Developer Center](#) provides unified access to documentation, BSPs, and development resources.

SECO's end-to-end AI deployment pipeline connects model training, deployment, and edge execution within a single workflow. By integrating **Edge Impulse** for AI model training and optimization with the **Clea** software framework for secure deployment and lifecycle management, SECO enables a smooth transition from proof of concept to production. AI models are optimized for Dragonwing platforms, securely deployed via Clea, and executed locally with low-latency inference, while updates, monitoring, and fleet management are handled centrally.

### SECO and Qualcomm Technologies: driving the future of Edge AI together

*"Our collaboration with Qualcomm Technologies plays a key role in advancing Edge AI across industrial and smart applications,"* said **Davide Catani, Chief Technology & Innovation Officer at SECO**. *"By combining Dragonwing platforms with SECO's system-level expertise and software enablement, we deliver scalable, high-performance edge solutions that help customers move from innovation to deployment faster and with confidence."*

*"SECO continues to lead the way in demonstrating how Dragonwing platforms elevate performance, efficiency, and intelligence at the industrial edge,"* said **Enrico Salvatori, Senior Vice President and President of Qualcomm Europe, Inc.** *"These solutions provide a powerful technology foundation to accelerate industrial innovation for next-generation HMI, factory automation, smart grid infrastructure, and other edge AI applications. We look forward to seeing SECO showcase these platforms at embedded world 2026."*



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A **speaker session by Douglas Benitez, Senior Director, Business Development at Qualcomm Europe** will also be hosted on March 11 at SECO's booth. Visitors are invited to join at **Booth 320, Hall 1**.

### SECO

SECO (IOT.MI) is a high-tech company that develops and manufactures cutting-edge solutions for the digitalization of industrial products and processes. SECO's hardware and software offerings enable B2B companies to easily introduce edge computing, Internet of Things, data analytics, and artificial intelligence to their businesses. SECO's technology spans across multiple fields of application, serving more than 450 customers across sectors such as medical, industrial automation, fitness, vending, transportation, and many others. Through live monitoring and smart control of in-the-field devices, SECO solutions contribute to low environmental impact business operations via a more efficient use of resources.

For more information: <http://www.seco.com/>

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